PIC INTERNATIONAL CONFERENCE

ANGELTECH

2025 AGENDA

Correct as of 18-May-2024 3:26pm
For the latest version of our agenda, visit picinternational.net

Day 1 - Monday 15th April 2024

18:30 **Pre-conference networking drinks reception**

Day 2 - Tuesday 16th April 2024

08:00 Registration and welcome refreshments

08:50 Housekeeping by Michael Lebby and David Cheskis - Conference Chairs

PIC Packaging: Securing Optimal Integration and Performance

09:00 Electrooptic Glass Substrates for Photonic Packaging
Presented by Andreas Matiss - Corning

09:15 Industry proven Photonic Wire Bonds and Facet-Attached Micro-Optical Elements: from Telecom/Datacom to Quantum Applications
Presented by Philipp-Immanuel Dietrich - Vanguard Automation

09:30 Optimizing Cost and Scaling Efficiency in Swept Wavelength Testing for Alignment and Packaging of PIC
Presented by Matt Adams - VIAVI Solutions

09:45 Advancing Optical Testing for Photonic Integrated Circuits: From Prototype to Production Scale-Up
Presented by Ricardo Arias - Luna Innovations

10:00 Towards a Comprehensive, Multiphysics Design Solution for Co-packaged Optics
Presented by Ahsan Alam - Ansys Optics

10:15 Aligned additive microfabrication for advanced optical packaging
Presented by Jochen Zimmer - Nanoscribe

10:30 Morning Break

11:00 Breaking the barriers for high frequency packaging
Presented by Guillermo Carpintero - LEAPWAVE TECHNOLOGIES

11:15 Technology Developments & Equipment Concepts for Scaling Up Photonics Production for Datacenters
Presented by Malte Ennen - ficonTEC

11:30 As Photonics Applications Multiply, New Ways to Subtract Costs
Presented by Scott Jordan - Physik Instrumente

11:45 Advances in PIC Manufacturing for Sensing and Datacom Applications – All Thanks to Nanoimprint Lithography
Presented by Jonas Khan - EV Group

12:00 AIM Photonics Foundry providing Co-Process and Co-Development to Address Challenges in Photonic Integrated Circuit (PIC) Packaging
Presented by David Harame - AIM Photonics

12:15 Impact of PIC device architecture and integration concept on packaging and assembly
Presented by Helen Waechter - Helbling Technik Bern AG

12:30 Advancing the Frontier of Photonic Integration: Challenges and Innovations in PIC Packaging
PHIX, Lightwave Logic Inc, Tyndall National Institute, and POET Technologies

13:00 Lunch Break

Hybrid PICs: Pioneering New Frontiers in Photonic Integration

Sponsored by OPTICA

14:15 Designing high power hybrid integrated tuneable lasers for automotive LiDAR
Presented by Ruud Oldenbeuving - imec

14:30 Advances in hybrid Silica-Nitride waveguides
Presented by Henk Bulthuis - Broadex Technologies

14:45 Unlocking the potential of hybrid/heterogeneous PIC design
Presented by Martin Fiers - Luceda Photonics

15:00 TFLN PIC Platform: Unleashing Monolithic power to Enhance Hybrid/Heterogeneous PICs
Presented by Hamed Sattari - CSEM

15:15 High speed, low power, tiny modulators in a polymer PIC platform are poised to enable 800G/1.6Tbps data communications, driven in part by artificial intelligence.
Presented by Michael Lebby - Lightwave Logic Inc

15:30 Advanced Photonic Integrated Circuit Testing: APEX Technologies' solution for High Precision Optical Instrumentation
Presented by Tomy Marest - APEX Technologies

15:45 BTO-powered PICs for communication and switching
Presented by Cyriel Minkenberg - Lumiphase

16:00 Afternoon Break

16:30 Heterogeneous integration to capitalize on upcoming markets, the new IPSR-I global roadmap update
Presented by Peter van Arkel - PhotonDelta

16:45 Advancements in Optically Enhanced MEMS Inertial Sensors: Prototyping and Roadmap Challenges for Consumer Markets (Video presentation)
Presented by Lia Li - Zero Point Motion

17:00 Augmented Silicon Photonics for demanding Data Center and AI/ML network fabrics
Presented by Yannick Paillard - SCINTIL Photonics

17:15	**Silicon-organic hybrid electro-optic modulators for next generation optical interconnects** *Presented by Adrian Mertens - SilOrix*
17:30	**Heterogeneous Integration of Photonic Devices on Silicon** *Presented by Jonathan Klamkin - UCSB (University of California Santa Barbara)*
17:45	**Photonic Integrated Circuits: Surface Coupling Lasers using InP as an integration platform** *Presented by Bill Ring - Vector Photonics*
18:00	**Sputter deposited Al2O3: an ultra-low loss integrated photonic platform for broadband operation from the UV till the mid-IR** *Presented by Sonia M. Garcia-Blanco - ALUVIA Photonics*
18:15	**Closing Remarks**
18:20	**Networking Drinks / Dinner Reception**

Day 3 - Wednesday 17th April 2024

08:00	Registration and welcome refreshments
08:50	Housekeeping by Michael Lebby and David Cheskis - Conference Chairs

Rapid Scaling: Foundries Fuelling PICs' Mass Production

09:00	A view from the Foundry: Silicon Photonics *Presented by Anthony Yu - GlobalFoundries*
09:15	Low Loss Photonic Integrated Circuits: From Prototype to Volume *Presented by Michael Geiselmann - LIGENTEC*
09:30	Silicon photonics for AI/HPC Optical Interconnects *Presented by Philippe Absil - imec*

Power Efficiency: Minimizing Consumption in PICs

09:45	The evolving role of optics in AI Clusters *Presented by Vlad Kozlov - LightCounting*

PIC Size and Simulation: Enhancing Design Efficiency

10:00	A perspective on recent trends in inverse design of integrated photonic devices and circuits *Presented by Wolfger Peelaers - Hewlett Packard Enterprise*
10:15	Efficient design techniques for custom PDKs protecting your IP *Presented by Andrzej Po?atynski - VPIphotonics*
10:30	Morning Break

Accelerating PIC Adoption in Established Markets

Sponsored by LioniX International

11:10	Design to Device: Accelerating PIC adoption by lowering entry barriers to turnkey photonic solutions *Presented by Amitesh Singh - LioniX*
11:25	Transforming point-of-care diagnostics: The power of silicon plasmonic biosensors in the battle against acute infections *Presented by Dimitris Tsiokos - bialoom*
11:40	Is integrated optics a perfect fit for next generation of Access Networks? *Presented by Prof. Dr. Antonio Teixeira - PICadvanced*
11:55	Innovate with Confidence: Strategies for reliable PIC design *Presented by Ronald Broeke - Bright Photonics*
12:10	Scaling photonic integration and packaging of hybrid multi-chip assemblies using 3D lithography *Presented by Dr. Laura Horan - Vanguard Automation*
12:25	Opportunities for Photonics in Datacenter and High-Performance Computing (HPC) Infrastructure *Presented by Remco Stoffer - Synopsys*
12:40	Lunch Break
13:55	Silicon Photonics Market and Applications: from Optical Transceivers to Emerging Uses *Presented by Eric Mounier - Yole Group*
14:10	Semiconductorization of Photonics using Silicon Optical Interposer *Presented by Raju Kankipati - POET Technologies*
14:25	Efficient Test of PICs for High-Performance Computing Applications *Presented by Daria Lavrova - Keysight Technologies*
14:40	Revolutionizing Architecture and Components for New Generation Energy-Efficient High-Density Photonic Integrated Coherent Transceivers *Presented by Tomoyuki Akiyama - PETRA/Fujitsu*
14:55	Opportunities and Challenges for Optics in AI Factories *Presented by Yannick De Koninck - NVIDIA*
15:10	PIC Solutions for Established and Novel Optical Communication Applications *Presented by Mehrdad Ziari - Infinera*
15:25	Opportunities for Silicon Photonics: Developments and Applications *Presented by James Falkiner - IDTechEx*
15:45	Closing Remarks

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NOTES